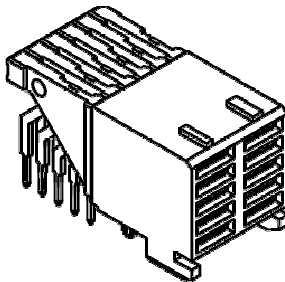


# **PerMet 2.0 5x2 Power PIH**

According to IEC 61076-4-104



- Designed according to the standard IEC 61076-4-104 in such a way that machine assembly and Reflow soldering is possible
- High contact density with 2 mm grid spacing
- 12 mm connector module
- Termination method: paste in hole

## PRODUCT DATA

### Electric data

Current rating	2.75 A max / contact
Test voltage	1000 V AC (rms)
Insulation resistance	5 Gohm (min)
Temperature range	-55... +125 °C

### Materials

Housing material	Thermoplastic resin, glass-fibre filled, UL 94 V-0
Contact material	Copper alloy
Contact plating	Gold over nickel or.. Gold flash over nickel palladium over nickel
Terminal plating	Tin over nickel

### Physical data

Mating force	1.50 N max / contact
Withdrawal Force	0.30 N min / contact

### PCB data

Recommended PCB hole platings	0.7 <sup>+0.07</sup> / <sub>-0.05</sub> mm Cu 25-50 µm, Sn or SnPb < 10 µm
PCB Thickness	1.6 – 2.4 mm

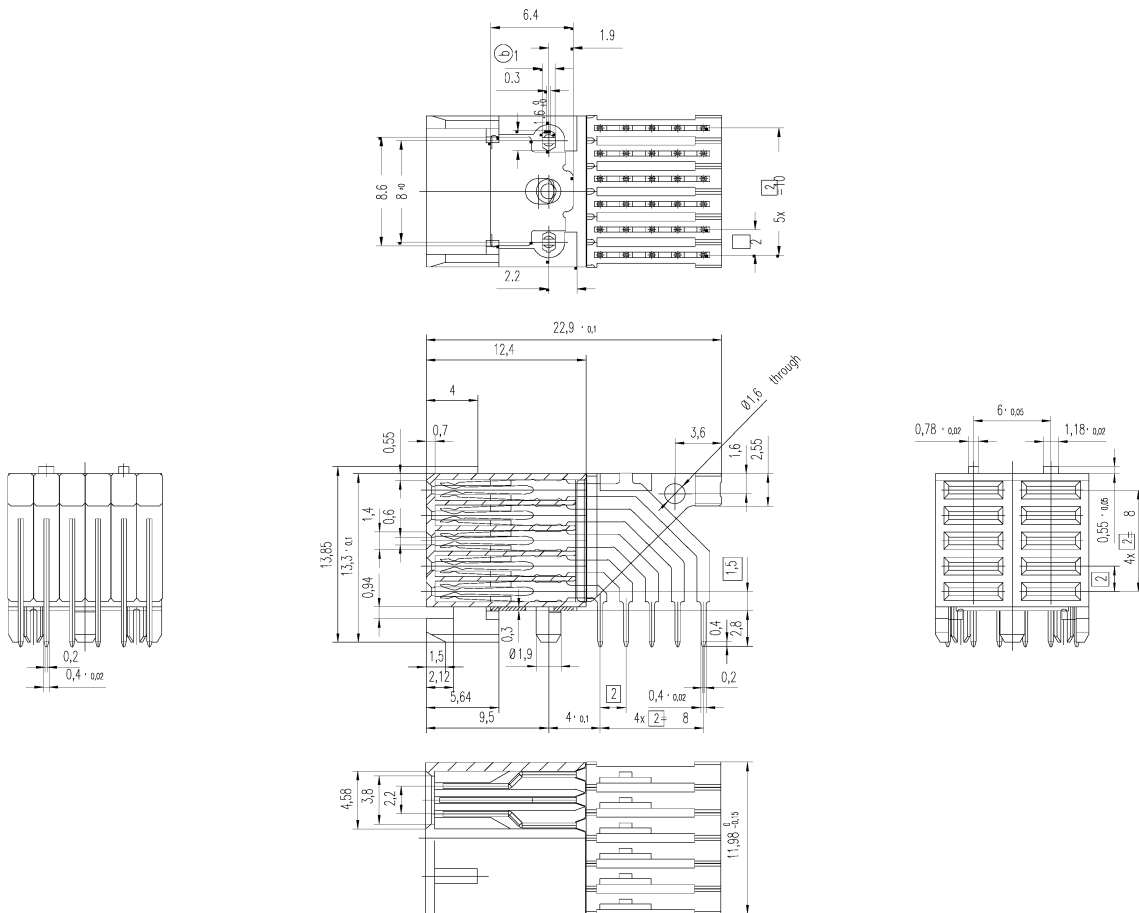
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## PerMet 2.0 5x2 Power PIH

Identification	Number of contacts	Part number
PerMet 2.0 5x2 Power PIH	10	F-P10



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